ABSTRACT

MULTI-CHIP MODULE PACKAGE

A repairable multi-chip module which is used when failures are found after an electrically and functionally testing is described. A substrate is provided. At least a first normal die having a plurality of first pads is mounted on the substrate, wherein the first normal die is surrounded by the pads. At least a failed die is mounted on the substrate. Several third pads and fourth pads are mounted on the substrate, wherein the third pads surrounds the first normal die and the failed die and the fourth pads surrounds the first pads. At least a second normal die having a plurality of second pads is stacked over the failed die. Several conductive wires are electrically connecting the first pads on the first normal die and the third pads. Several reworking conductive wires are electrically connecting the second pads on the second normal die and the fourth pads.

FIGURE 3F